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Vishay General Semiconductor

Photovoltaic Solar Cell Protection Schottky Rectifier

Ultra Low $V_F = 0.30$ V at $I_F = 5.0$ A



PRIMARY CHARACTERISTICS				
I _{F(AV)}	20 A			
V _{RRM}	45 V			
I _{FSM}	250 A			
V_F at $I_F = 20$ A	0.42 V			
T _{OP} max. (AC mode)	150 °C			
T _J max. (DC forward current)	200 °C			
Package	P600			
Diode variation	Single die			

FEATURES

- Trench MOS Schottky technology
- Low forward voltage drop, low power losses
- High efficiency operation
- High forward surge capability
- ESD capability
- Solder dip 275 °C max. 10 s, per JESD 22-B106
- T_J 200 °C max. in solar bypass mode application
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

MECHANICAL DATA

Case: P600

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test

Polarity: Color band denotes cathode end

MAXIMUM RATINGS ($T_A = 25 \text{ °C}$ unless otherwise noted)					
PARAMETER SYN		VSB2045	UNIT		
Device marking code		V2045			
Maximum repetitive peak reverse voltage	V _{RRM}	45	V		
Maximum average forward rectified current (fig. 1)	I _{F(AV)} ⁽¹⁾	20	Α		
	I _{F(AV)} ⁽²⁾	6.5	A		
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	250	А		
Operating junction temperature range	T _{OP}	-40 to +150	°C		
Storage temperature range	T _{STG}	-40 to +175	°C		
Junction temperature in DC forward current without reverse bias, $t \leq 1 \ h$	T _J ⁽³⁾	≤ 200	°C		

Notes

⁽¹⁾ With heatsink

(2) With heatsink, free air

⁽³⁾ Meets the requirements of IEC 61215 ed. 2 bypass diode thermal test

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ROHS COMPLIANT

HALOGEN

FREE



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)							
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT	
Instantaneous forward voltage	I _F = 5.0 A	T _A = 25 °C	– V _F ⁽¹⁾	0.44	-	v	
	I _F = 10 A			0.46	-		
	I _F = 20 A			0.50	0.58		
	I _F = 5.0 A	T _A = 125 °C		0.30	-		
	I _F = 10 A		T _A = 125 °C		0.35	-	
	I _F = 20 A			0.42	0.50		
Reverse current	V _B = 45 V	T _A = 25 °C T _A = 125 °C	$T_{A} = 25 \text{ °C}$ I_{B} (2)	23.4	1200	μA	
	$v_{\rm R} = 45 v$		'R (=/	11.9	35	mA	
Typical junction capacitance	4.0 V, 1 MHz		CJ	2050	-	pF	

Notes

 $^{(1)}\,$ Pulse test: 300 μs pulse width, 1 % duty cycle

⁽²⁾ Pulse test: 40 ms pulse width

THERMAL CHARACTERISTICS ($T_A = 25 \text{ °C}$ unless otherwise noted)				
PARAMETER	SYMBOL	VSB2045	UNIT	
Thermal resistance	R _{0JA} ⁽¹⁾	55	°C/W	
	R _{0JL} ⁽¹⁾	3.5		
Typical thermal resistance	R _{0JL} ⁽²⁾	2.5	°C/W	

Notes

⁽¹⁾ Without heatsink, free air; units mounted on PCB with 2 mm x 2 mm copper pad areas at 9.5 mm lead length

⁽²⁾ Leads clipped at 3 mm lead length from plastic body on 7.0 cm x 2.2 cm x 1.9 cm x 2 heatsink

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS

$(T_A = 25 \text{ °C unless otherwise noted})$							
STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE		
JESD22-A114	Human body model (contact mode)	C = 150 pF, R = 1.5 Ω		3B	> 8 kV		
JESD22-A115	Machine model (contact mode)	C = 200 pF, R = 0 Ω	V _C	С	> 400 V		
IEC 61000-4-2 (2)	Air discharge mode ⁽¹⁾	C = 150 pF, R = 330 Ω		4	> 15 kV		

Notes

⁽¹⁾ Immunity to IEC 61000-4-2 air discharge mode has a typical performance > 25 kV

(2) System ESD standard

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
VSB2045-M3/54	1.88	54	800	13" diameter paper tape and reel		
VSB2045-M3/73	1.88	73	300	Ammo pack packaging		



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RATINGS AND CHARACTERISTICS CURVES ($T_A = 25$ °C unless otherwise noted)

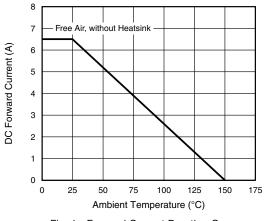


Fig. 1 - Forward Current Derating Curve

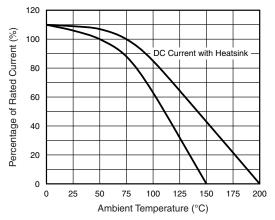


Fig. 2 - Rated Forward Current vs. Ambient Temperature

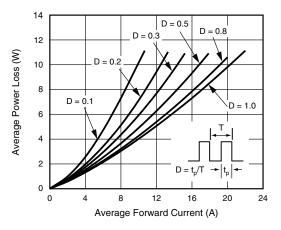


Fig. 3 - Forward Power Loss Characteristics

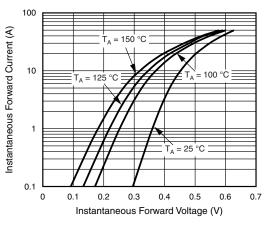


Fig. 4 - Typical Instantaneous Forward Characteristics

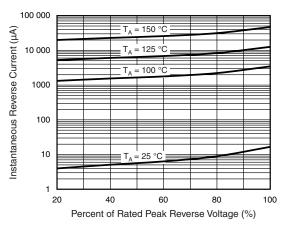


Fig. 5 - Typical Reverse Leakage Characteristics

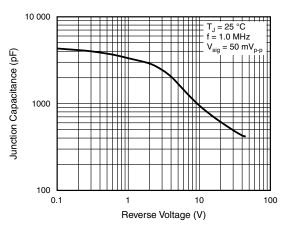


Fig. 6 - Typical Junction Capacitance

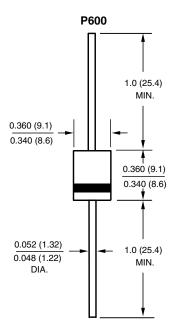
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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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